



In the United States Patent and Trademark Office

Serial Number: 10/728,930
Application. Filed: December 8, 2003
Applicant: Kia Silverbrook
Application. Title: Molded Wafer Scale Cap Array
Examiner/GAU: David Nhu/2818

Dated August 22, 2005
At: Balmain, NSW
Docket No. ZG115US

AMENDMENT A

Commissioner for Patents
Washington, District of Columbia 20231

Dear Sir:

In response to the Office Action of July 8, 2005, please amend the above-identified application as follows:

Amendments to the Specification begin on page 2 of this paper. The Applicant submits that these amendments introduce no new matter.

Amendments to the Claims begin on page 3 of this paper. The Applicant submits that these amendments introduce no new matter.

Remarks/Arguments begin on page 7 of this paper.